IC Packaging Markets

2018 Global Report Series

Complex multi-component and multi-layered packages have added a new dimension and cost to high speed performance to integrated circuits (ICs) in terms of their function and small form factor, thus making them game changers for the electronics manufacturing industry overall. It is the package of the IC which controls the device footprint to the printed circuit board (PCB), thereby enabling a multitude of small and new, handheld electronics computing and communicating IC devices to be invented and proliferate in today's emerging markets.

New Venture Research (NVR) is pleased to announce its continuing coverage of the IC packaging market with two new reports in 2018, ***The Worldwide IC Packaging Market–2018 Edition*** and ***Advanced IC Packaging Technologies, Materials, and Markets–2018 Edition***. Each report has a different focus, thus allowing the reader to analyze the world of IC packaging from a number of market perspectives, in a unique report that combines special information to meet individual market research needs.

The first report, **The Worldwide IC Packaging Market –2018 Edition**, presents NVR's annual forecast for each of the major package families by semiconductor product type (2017-2022). This information is then totaled and segmented in detail. The report also presents NVR's continuing, extensive coverage of the evolving outsourced assembly and test (OSAT) contractor market.

The second innovative report, **Advanced IC Packaging Technologies, Materials, and Markets–2018 Edition,** analyzes critical advanced IC packaging methods, primarily aimed at the mobile handheld consumer market, while also including some leading material analysis of IC packaging sets and design features.

The IC Packaging series will provide readers with an effective tool for assessing the future trends in this growing new market. Please review each report's summary Table of Contents on the following page for more detail.

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The Worldwide IC Packaging Market - 2018 Edition

Chapter 1: Introduction

Chapter 2: Executive Summary

Chapter 3: The State of the Industry

Chapter 4: Worldwide IC Packaging Market Analysis and Forecasts - 2017-2022

Chapter 5: IC Package Market Analysis and Forecasts by Semiconductor Device - 2017-2022

Chapter 6: IC Package Market Analysis and Forecasts by Packaging Family - 2017-2022

Chapter 7: OSAT Market Analysis and Forecasts

Chapter 8: Company Profiles

Published February 2018, 400+ pages

Advanced IC Packaging Technologies, Materials, and Markets - 2018 Edition

Chapter 1: Introduction

Chapter 2: Executive Summary

Chapter 3: Overview of IC Packaging Markets Worldwide

Chapter 4: Interconnection Technologies

Chapter 5: Multichip Packages

Chapter 6: System-in-Package Solutions & Substrate Materials

Chapter 7: Advanced Single-Chip Packages

Chapter 8: Company Profiles

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About the Author

Jerry Watkins is an independent senior analyst with more than 20 years of experience in the field of market research and consulting. He has worked for leading research companies such as Frost & Sullivan, Lucid Information Services, and NSI Research both in management and as a writer. Mr. Watkins has authored many syndicated reports, previously in the telecommunications sector and more recently in the computing, merchant embedded computing industry, as well as two IC packaging related reports in since 2014. He holds two university degrees including a B.A. in History, as well as a M.A. in International Studies.